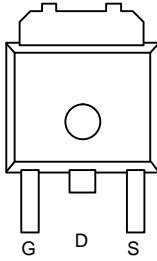


## IRFR3418TRPBF-VB Datasheet

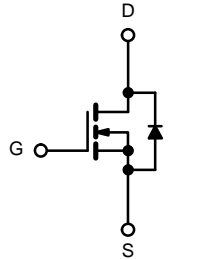
### N-Channel 80 V (D-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) Max.	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
80	0.0050 at V <sub>GS</sub> = 10 V	75 <sup>a</sup>	17.1 nC
	0.0070 at V <sub>GS</sub> = 6.0 V	65 <sup>a</sup>	
	0.0087 at V <sub>GS</sub> = 5.0 V	54	

TO-252



Top View



N-Channel MOSFET

#### FEATURES

- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

#### APPLICATIONS

- Primary Side Switching
- Synchronous Rectification
- DC/AC Inverters
- LED Backlighting



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	80	V
Gate-Source Voltage	V <sub>GS</sub>	± 20	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	T <sub>C</sub> = 25 °C	75 <sup>a</sup>
		T <sub>C</sub> = 70 °C	62.7
		T <sub>A</sub> = 25 °C	28.6 <sup>b, c</sup>
		T <sub>A</sub> = 70 °C	24.9 <sup>b, c</sup>
Pulsed Drain Current (t = 100 μs)	I <sub>DM</sub>	150	A
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	
		T <sub>A</sub> = 25 °C	4.5 <sup>b, c</sup>
Single Pulse Avalanche Current	I <sub>AS</sub>	30	mJ
Single Pulse Avalanche Energy	E <sub>AS</sub>	45	
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25 °C	62.5
		T <sub>C</sub> = 70 °C	40
		T <sub>A</sub> = 25 °C	5 <sup>b, c</sup>
		T <sub>A</sub> = 70 °C	3.2 <sup>b, c</sup>
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>		260	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, f</sup>	R <sub>thJA</sub>	20	25	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	1.5	2.0	

#### Notes

- Package limited.
- Surface mounted on 1" x 1" FR4 board.
- t = 10 s.
- The TO-220 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under steady state conditions is 70 °C/W.

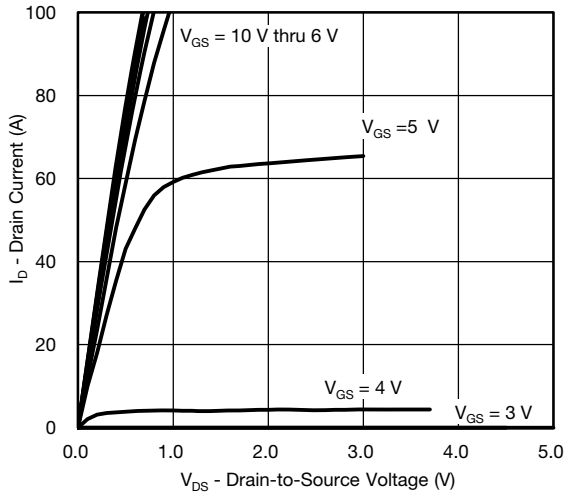
<b>SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	80			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		37		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			-6.1		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.5		4.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	30			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 20\text{ A}$		0.0050		$\Omega$
		$V_{GS} = 6\text{ V}, I_D = 15\text{ A}$		0.0070		
		$V_{GS} = 5.0\text{ V}, I_D = 10\text{ A}$		0.0087		
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 10\text{ V}, I_D = 20\text{ A}$		60		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		1855		pF
Output Capacitance	$C_{oss}$			950		
Reverse Transfer Capacitance	$C_{rss}$			76		
Total Gate Charge	$Q_g$	$V_{DS} = 40\text{ V}, V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		35.5	54	nC
		$V_{DS} = 40\text{ V}, V_{GS} = 6\text{ V}, I_D = 10\text{ A}$		22	33	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 40\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 10\text{ A}$		17.1	26	
			Gate-Drain Charge	$Q_{gd}$		
Output Charge	$Q_{oss}$					
					$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}$	
Gate Resistance	$R_g$		$f = 1\text{ MHz}$	0.5	1.3	2
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 40\text{ V}, R_L = 4\text{ }\Omega$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		12	24	ns
Rise Time	$t_r$			8	16	
Turn-Off Delay Time	$t_{d(off)}$			32	64	
Fall Time	$t_f$			7	14	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 40\text{ V}, R_L = 4\text{ }\Omega$ $I_D \cong 10\text{ A}, V_{GEN} = 6.0\text{ V}, R_g = 1\text{ }\Omega$		14	28	
Rise Time	$t_r$			11	22	
Turn-Off Delay Time	$t_{d(off)}$			30	60	
Fall Time	$t_f$			8	16	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$			75	A
Pulse Diode Forward Current ( $t = 100\text{ }\mu\text{s}$ )	$I_{SM}$				150	
Body Diode Voltage	$V_{SD}$	$I_S = 5\text{ A}$		0.76	1.1	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		38	75	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			36	70	nC
Reverse Recovery Fall Time	$t_a$			19		ns
Reverse Recovery Rise Time	$t_b$			19		

**Notes**

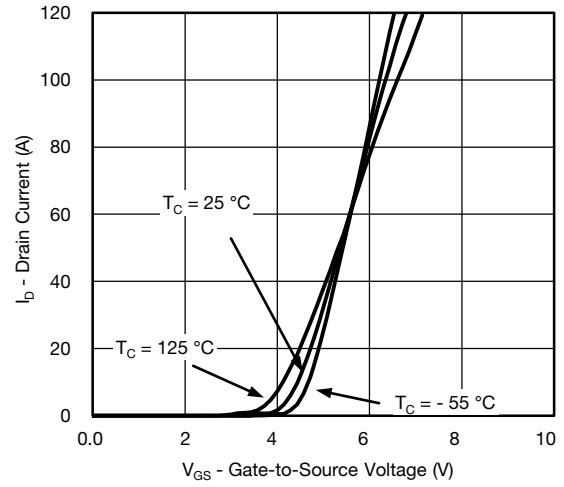
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

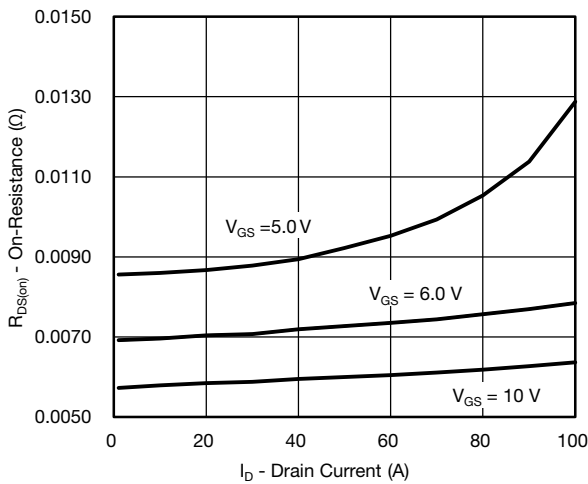
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



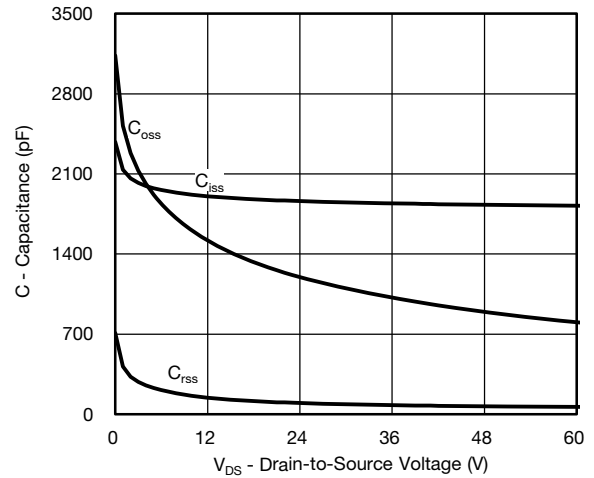
**Output Characteristics**



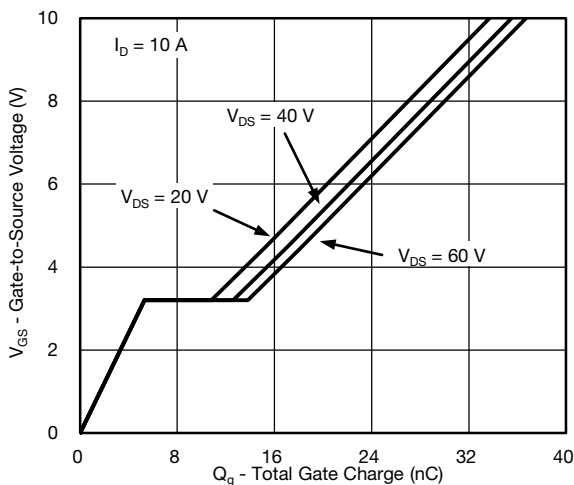
**Transfer Characteristics**



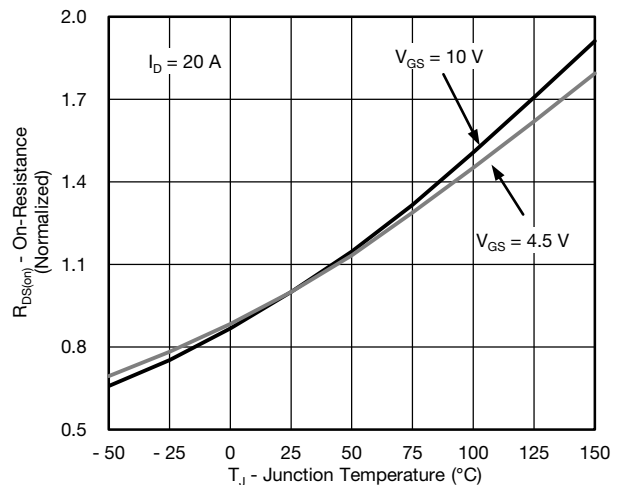
**On-Resistance vs. Drain Current**



**Capacitance**

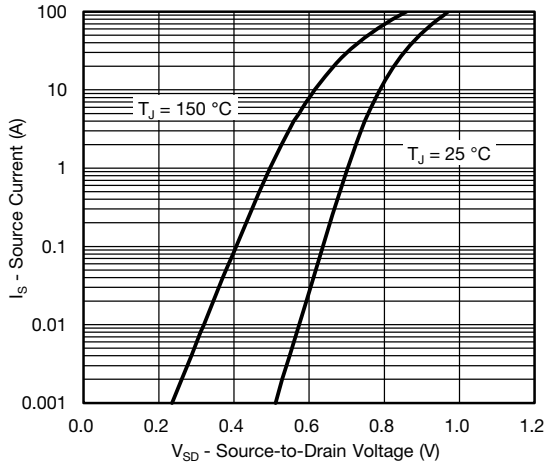


**Gate Charge**

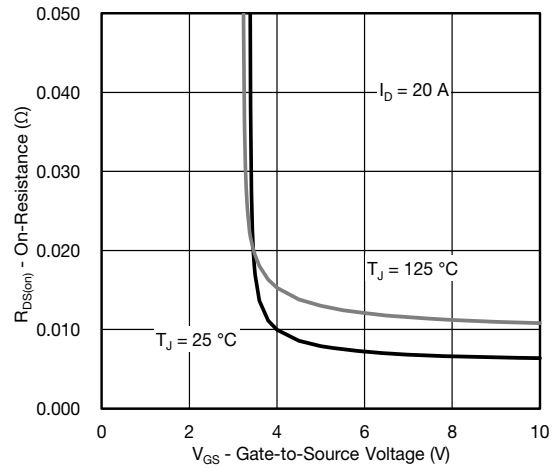


**On-Resistance vs. Junction Temperature**

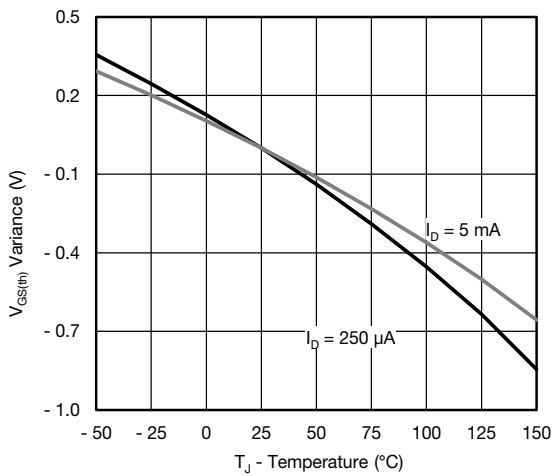
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



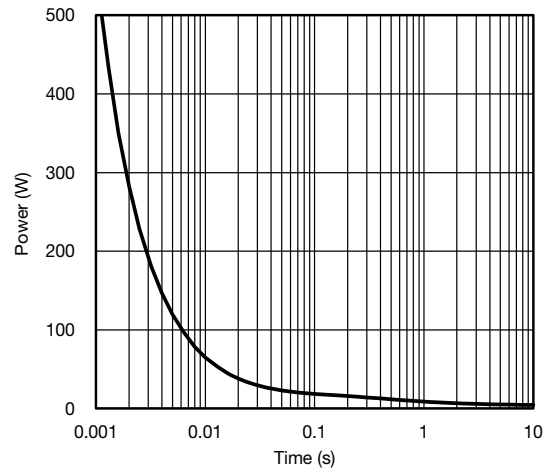
**Source-Drain Diode Forward Voltage**



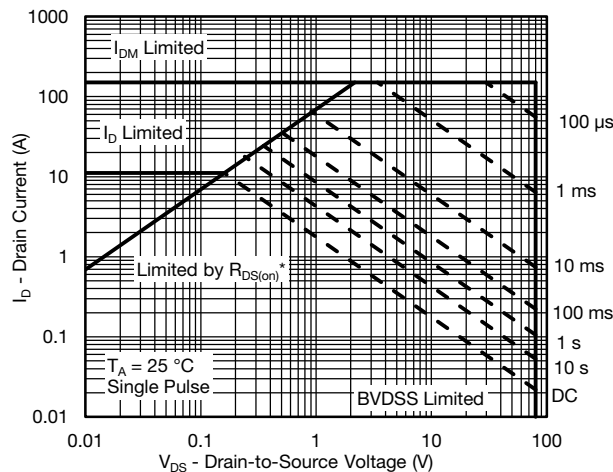
**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**



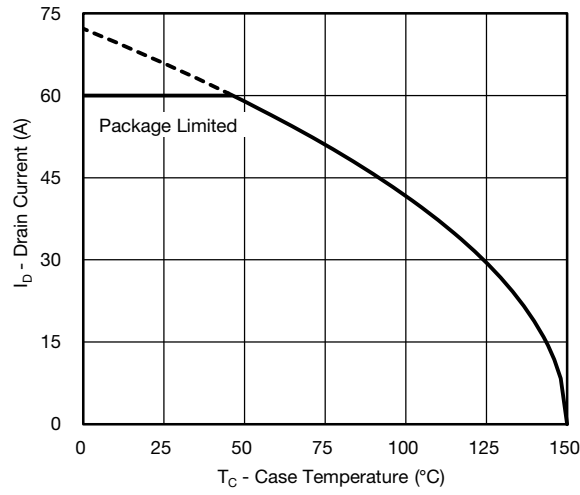
**Single Pulse Power, Junction-to-Ambient**



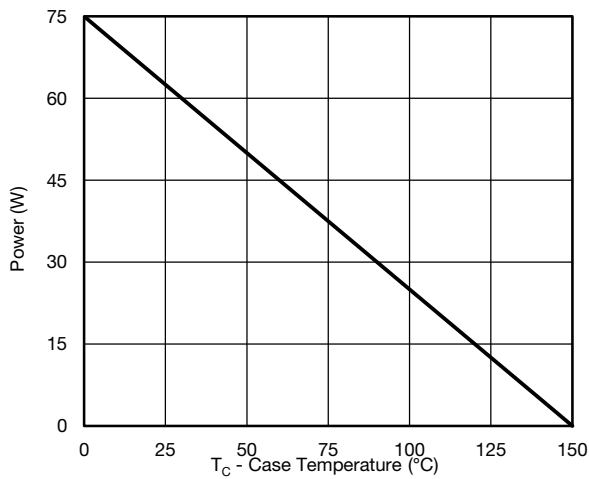
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

**Safe Operating Area, Junction-to-Ambient**

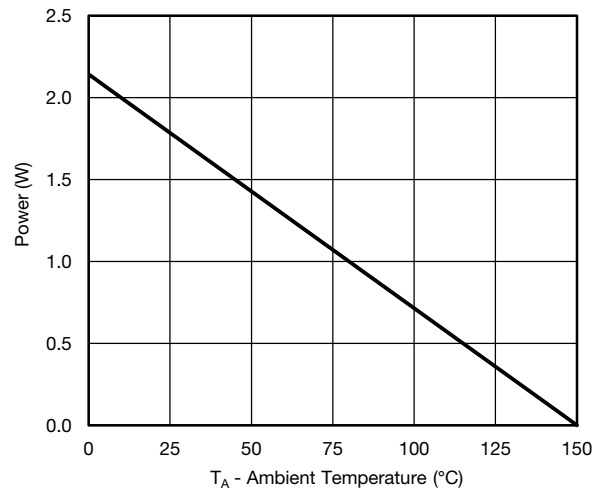
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Current Derating\***



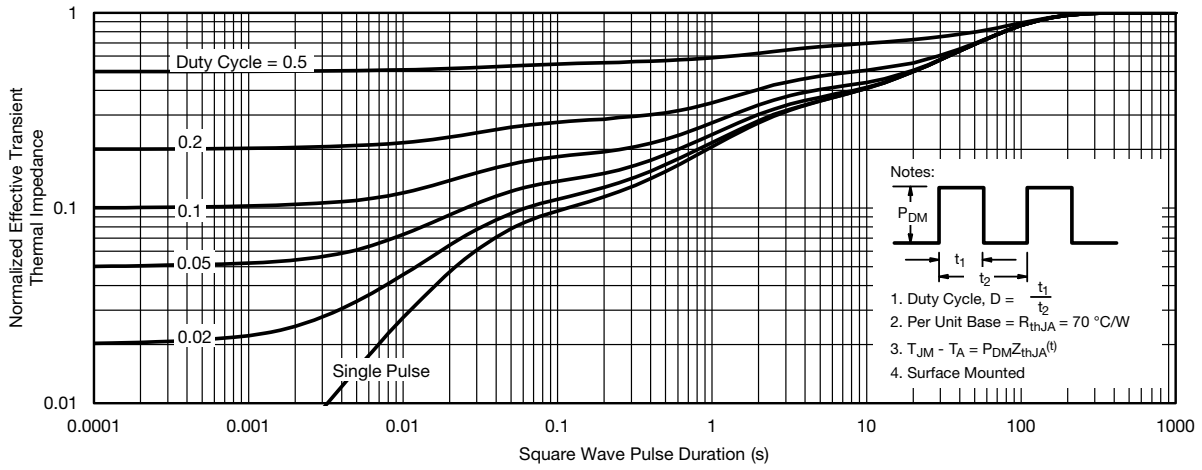
**Power, Junction-to-Case**



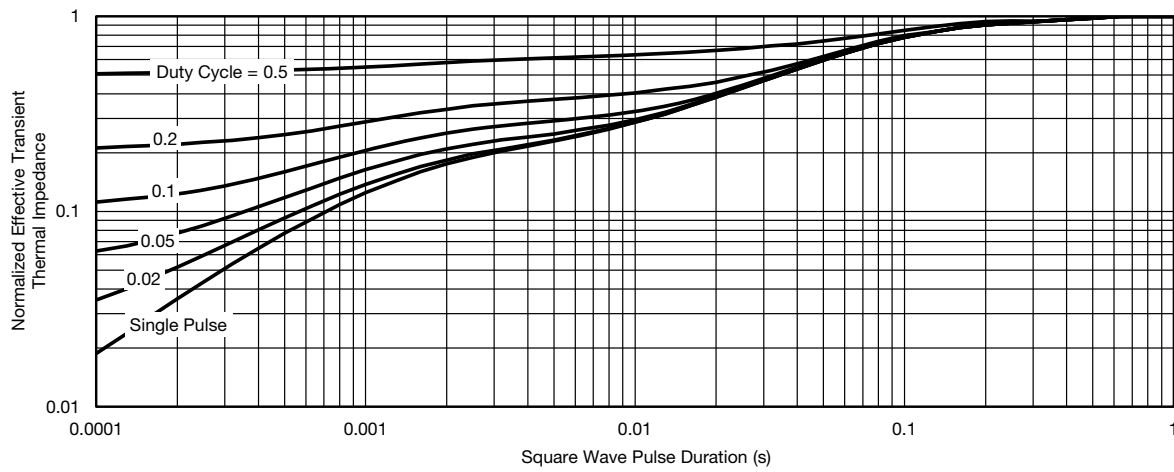
**Power, Junction-to-Ambient**

\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150\text{ }^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

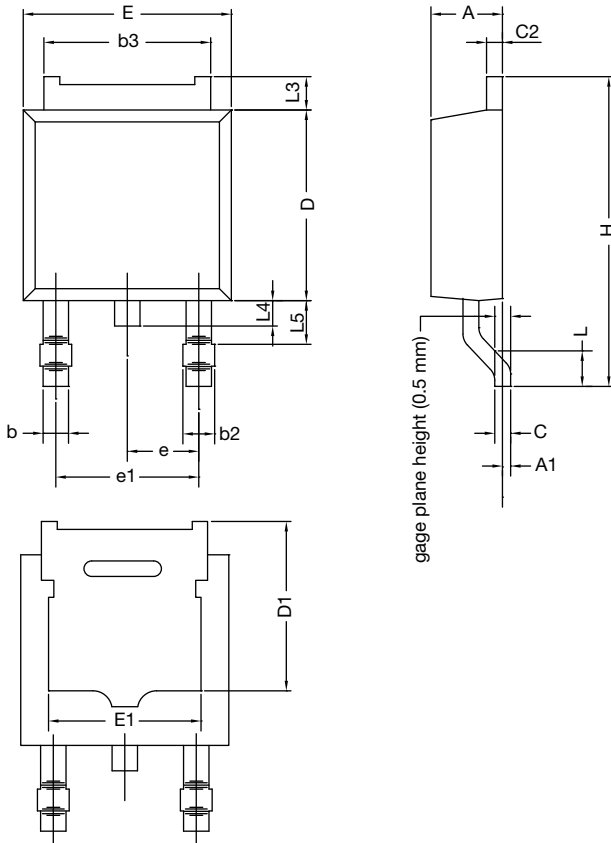


**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Case**

## TO-252AA CASE OUTLINE

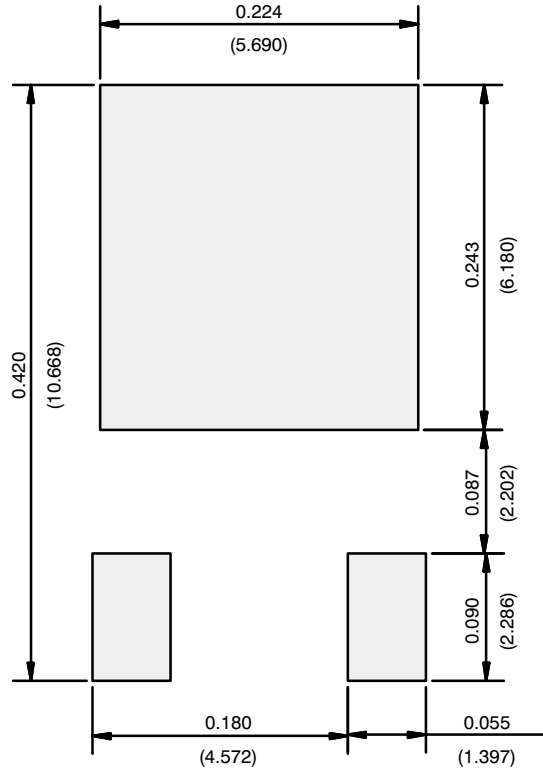


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
C	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	5.21	-	0.205	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
H	9.40	10.41	0.370	0.410
e	2.28 BSC		0.090 BSC	
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.14	1.52	0.045	0.060
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347				

**Note**

- Dimension L3 is for reference only.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads  
Dimensions in Inches/(mm)



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